

10/594548**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE****IAP5 Rec'd PCT/PTO 27 SEP 2006**

Applicants: H. KOMATSU, et al.

Serial No.: NEW

Filed: SEPTEMBER 27, 2006

For: HEAT-RESISTANT PHOTSENSITIVE RESIN
COMPOSITION, METHOD FOR FORMING PATTERN USING
THE COMPOSITION, AND ELECTRONIC PART**PRELIMINARY AMENDMENT****Mail Stop: NEW APPS**
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 27, 2006

Sir:

Please amend the above-identified application, prior to calculation of the filing fee, as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE SPECIFICATION;

AMENDMENTS TO THE CLAIMS;

REMARKS are included following the amendments; and

As an Appendix, a clean copy of the Substitute Specification and a marked-up copy of the original specification (showing changes made to the original specification, in the Substitute Specification) are enclosed.